

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-18. (Cancelled)

19. (Previously Presented) A packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit including a pressure sensor;

a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over the pressure sensor of the electronic device such that the pressure sensor can be at least partially activated from outside of said protective package; and

a projecting portion of elastic material projecting from a surface of the electronic device into the window, the projecting portion being structured to enable the pressure sensor to be activated through the projecting portion when the electronic device is in use, wherein said projecting portion is shaped to form a ring on the electronic circuit.

20. (Cancelled)

21. (Previously Presented) The packaged electronic device according to claim 19 wherein said window has tapering walls toward said electronic circuit.

22. (Previously Presented) A packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit;

a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over a portion of the electronic device such that the electronic device can be at least partially activated from outside of said protective package; and

a projecting portion of elastic material projecting from a surface of the electronic device into the window, the projecting portion being structured to enable the electronic device to be activated through the projecting portion when the electronic device is in use, wherein said projecting portion is surrounded by dyke or barrier formed on a surface of the electronic circuit.

23. (Cancelled)

24. (Previously Presented) The packaged electronic device of claim 19 wherein the electronic circuit includes a proximity sensor.

25. (Cancelled)

26. (Cancelled)

27. (Previously Presented) A packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit including a pressure sensor;

a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over the pressure sensor such that the pressure sensor can be activated from outside of said protective package; and

an elastic protective layer positioned in the window, the protective layer being structured to enable the pressure sensor to be activated through the protective layer when the electronic device is in use, wherein the protective layer is shaped to form a ring on the electronic circuit.

28. (Previously Presented) The packaged electronic device of claim 27 wherein the window has walls tapering toward said electronic circuit.

29. (Previously Presented) A packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit;

a plastic protective package surrounding and supporting the electronic circuit, the protective package having a window over a portion of the electronic device such that the electronic device can be activated from outside of said protective package; and

an elastic protective layer positioned in the window, the protective layer being structured to enable the electronic device to be activated through the protective layer when the electronic device is in use, wherein the protective layer is surrounded by dyke or barrier formed on a surface of the electronic circuit.

30. (Cancelled)

31. (Previously Presented) A packaged electronic device ready for electronic use, comprising:

a semiconductor-integrated electronic circuit having a top, a bottom, and lateral sides extending between the top and bottom;

an elastic protective layer positioned on the circuit, the protective layer being structured to enable the electronic device to be activated through the protective layer when the electronic device is in use; and

a plastic protective package in which the electronic circuit is embedded, the protective package supporting the electronic circuit and contacting the lateral sides of the electronic circuit, the protective package having a window over a portion of the electronic circuit such that the electronic circuit can be activated from outside of said protective package, wherein the protective layer is surrounded by dyke or barrier formed on a surface of the electronic circuit.

32. (Previously Presented) The device of claim 31 wherein the protective package also contacts the top of the electronic circuit adjacent to the window.

33. (Previously Presented) The device of claim 31 wherein the window is define by tapering walls that taper inwardly toward said electronic circuit.

34. – 35. (Cancelled)

36. (Previously Presented) The device of claim 31 wherein the electronic circuit includes a proximity sensor.

37. (Cancelled)

38. (Previously Presented) The device of claim 31 wherein the protective layer is shaped to form a ring on the electronic circuit.

39. (Cancelled)

40. (New) The device of claim 22 wherein the window is defined by tapering walls that taper inwardly toward said electronic circuit.

41. (New) The device of claim 22 wherein the electronic circuit includes a proximity sensor.

42. (New) The device of claim 29 wherein the window is defined by tapering walls that taper inwardly toward said electronic circuit.

43. (New) The device of claim 29 wherein the electronic circuit includes a proximity sensor.

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Reply to Office Action dated October 18, 2005

Amendments to the Drawings:

The attached sheet of drawings is a formal version of Figures 2A-2B, as amended in the Amendment filed on December 3, 2002, which was approved in the Office Action dated March 13, 2003.

Attachment: Replacement Sheet